Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(US-20040070053-$).did.	US-PGPUB	OR	OFF	2005/11/30 16:09
L2	1	1 and flexible	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:09
L3	47	("2544646" | "2767973" | "2793028" | "2947067" | "3226981" | "3382724" | "3382726" | "3572089" | "3710629" | "3713088" | "3739202" | "3744322" | "3813505" | "3842681" | "3859847" | "3897690" | "3897997" | "3902374" | "3924475" | "4009607" | "4056163" | "4091679" | "4104920" | "4155257" | "4199990" | "4221131" | "4258577" | "4281384" | "4311046" | "4342227" | "4345474" | "4445376" | "4457173" | "4462254" | "4483194" | "4510802" | "4512192" | "4533100" | "4590801").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/30 16:30
L4	5	L3 and silicon	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/30 16:30
L5	4	flexible adj silicon adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L6	524	flexible adj substrate with silicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L7	56	"5531002" or "5406848" or "5421213"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/11/30 16:30
L8	37	L7 and groove	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/11/30 16:30

L10	46	"5808198" or "5490421" or "3860949" or "4984063"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L11	19	L10 and flex$5 and silicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L12	386	vibration adj sensor and groove	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L13	137294	silicon adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L14	23	L12 and L13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L16	4	US-5808198-$ or US-5490421-$ or JP-11148946-$ or JP-09304424-$	USPAT; JPO	OR	OFF	2005/11/30 16:30
L17	136	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L18	249	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) not (((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L19	385	(bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30

L20	1761	((bend bending bended) and silicon and (groove trench) and (bond bonded bonding)) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L21	8731	(bend bending bended) and silicon and (groove trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L22	4863	(bend bending bended) and silicon and (groove trench) and (bond bonded bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:30
L23	147	(257/668,669,674,738).CCLS. and @pd>"20050719"	US-PGPUB; USPAT	OR	OFF	2005/11/30 16:32
L24	36	L6 and @pd>"20050719" not okada	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:32